(Status) (patented, pending, abandoned)

A, W, H, McL & N Docket No.

Applications)

Declaration For U.S. Patent Application

As a below named inventor, I hereby declare that:

*My residence, post office address and citizenship are as stated below next to my name.

names are listed be (Insert Title) ADS	original, first and sole inventor (if onl low) of the subject matter which is cl ORBENT FOR TRANSFORMING G	aimed and for which a patent ROWTH FACTOR-B, MET	is sought on the invention entitle HOD FOR REMOVING THE	ed	
	SFORMING GROWTH FACTOR-B which is attached hereto unless the f		DSORBER PACKED WITH THE	ADSORBENT	
the spectrication of	which is attached hereto unless the i	onowing is checked.			
v	vas filed on	as Unit	as United States Application Number or PCT International		
	Application Number	and was amended on			
	if applicable).				
by any amendment	I have reviewed and understand the coreferred to above. duty to disclose information which is r			,	
I hereby claim fore inventor's certifica	ign priority benefits under Title 35, Ute listed below and have also identified to the application on which priority	Inited States Code, § 119 (a)	- (d) of any foreign application(s)	for patent or	
43	35150 (2000	Japan	14/0/0000	Priority Claimed	
(List prior	35168/2000 (Number)	(Country)	(Day/Month/Year Filed)	_ 🛚 Yes 🗅 No	
foreign applications.	(Number)	(Country)	(Day/Month/ fear Filed)	☐ Yes ☐ No	
See note A	(Number)	(Country)	(Day/Month/Year Filed)	6	
on back of	(Number)	(Country)	(Day/Month/Year Filed)	_ □ Yes □ No	
this page)	(italiber)	(Country)	(Day/Monde Teat 1 fled)	☐ Yes ☐ No	
200	(Number)	(Country)	(Day/Month/Year Filed)		
(See note B on bac	k of this page) See atta	ched list for additional prior	foreign applications		
I hereby claim the	benefit under Title 35, United States (-	0 11	isted below.	
	(Application Num	ber)	(Filing Date)	_	
	(Application Num	ber)	(Filing Date)		
subject matter of ea the first paragraph ity as defined in Ti	benefit under Title 35, United States of the of the claims of this application is of Title 35, United States Code, § 112 tle 37, Code of Federal Regulations, § PCT international filing date of the a	not disclosed in the prior Un , I acknowledge the duty to d 1.56 which became available	ited States application in the man lisclose information which is mate	ner provided by erial to patentabil-	
(List Prior U.S.	(Application Serial Number)	(Filing Date)	(Status) (patented, pendir	ig, abandoned)	

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

(Application Serial Number)

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(Filing Date)

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the United States Code, § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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